



p–n Junction

- ► 3.1 THERMAL EQUILIBRIUM CONDITION
- > 3.2 DEPLETION REGION
- > 3.3 DEPLETION CAPACITANCE
- 3.4 CURRENT-VOLTAGE CHARACTERISTICS
- → > 3.5 CHARGE STORAGE AND TRANSIENT BEHAVIOR
- → ► 3.6 JUNCTION BREAKDOWN
 - ► 3.7 HETEROJUNCTION
 - SUMMARY

(رفتار گذرا) 3.5.3 Transient Behavior

*For switching applications, the forward-to-reverse-bias transition must be nearly

abrupt and the transient time should be short.

Figure 20a shows a simple circuit where a forward current I_F flows through a p-n junction.

At time *t* = 0, switch S is suddenly thrown to the right and an initial reverse current

 $I_R \cong V/R$ flows.

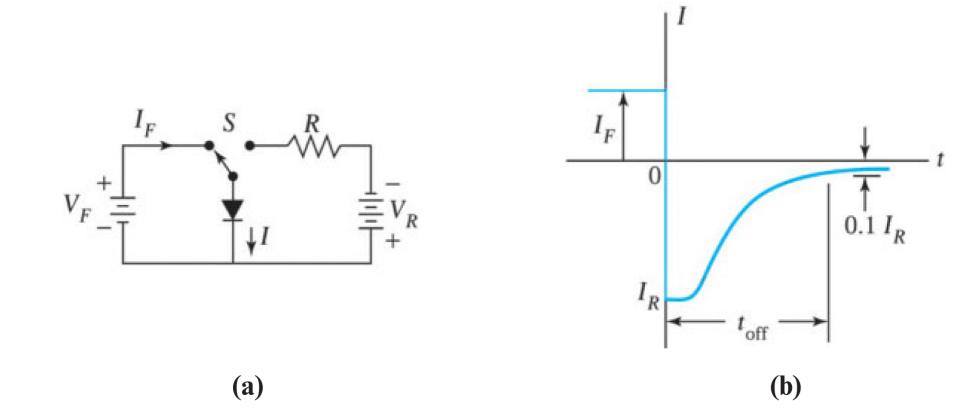


Fig. 20 Transient behavior of a p-n junction. (*a*) Basic switching circuit. (*b*) Transient response of the current switched from forward bias to reverse bias.

The transient time t_{off} , plotted in Fig. 20b, is the time required for the current to

reach 10% of the initial reverse current IR.

The transient time may be estimated as follows.

*Under the forward-bias condition, the stored minority carriers in the *n*-region for a

 p^+ –*n* junction is given by Eq. 76:

$$Q_p = \frac{L_p^2}{D_p} J_p(x_n) = \tau_p J_p(x_n).$$
$$Q_p = \tau_p J_p = \tau_p \frac{I_F}{A},$$

(76)

 \diamond where I_F is the total forward current and A is the device area.

If the average current flowing during the turn-off period is I_{R,ave}, the turn-off time is

the length of time required to remove the total stored charge Q_{ρ} :

$$t_{off} \cong \frac{Q_p A}{I_{R,\text{ave}}} = \tau_p \left(\frac{I_F}{I_{R,\text{ave}}}\right).$$
(80)

Thus the turn-off time depends on both the ratio of forward to reverse currents and

the lifetime of the minority carriers.

ا میانگین جریان معکوس مطابق شکل ۲۰ بین جریان ماکزیمم IR و IN %10 می باشد *The result of a more precise turn-off time calculation taking into account the time-

dependent minority-carrier diffusion problem is shown in Fig. 21.

*For fast-switching devices, we must reduce the lifetime of the minority carriers.

Therefore, we usually introduce recombination-generation centers that have energy

levels located near mid-bandgap, such as gold in silicon.

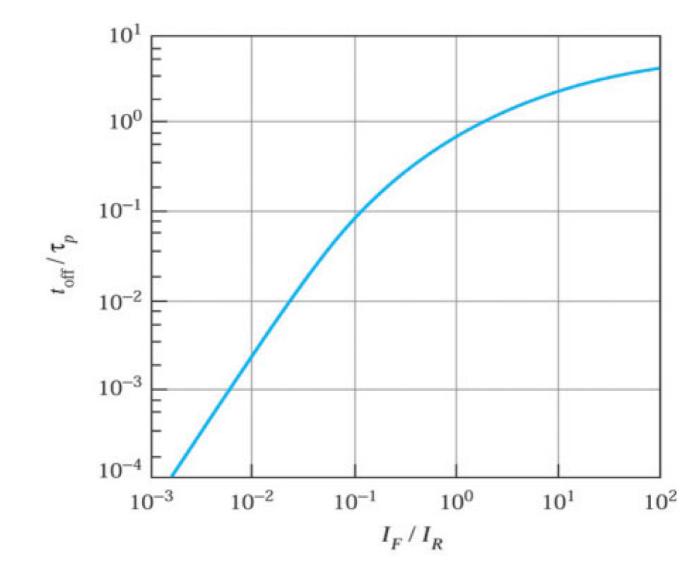


Fig. 21 Normalized transient time versus the ratio of forward current to reverse current.



*When a sufficiently large reverse voltage is applied to a p-n junction, the junction

breaks down and conducts a very large current.

المخرب), the Although the breakdown process is not inherently(ذاتاً) destructive(مخرب), the

maximum current must be limited by an external circuit to avoid excessive(بيش از

اندازه) junction heating.

Two important breakdown mechanisms are the tunneling effect and avalanche

multiplication(تكثير بهمنى).

*We consider the first mechanism briefly and then discuss avalanche multiplication in

detail, because avalanche breakdown imposes an upper limit on the reverse bias for

most diodes.

Avalanche breakdown also limits the collector voltage of a bipolar transistor (Chapter)

4) and the drain voltage of a MOSFET (Chapters 5 and 6).

In addition, the avalanche multiplication mechanisms can generate microwave

power, as in an IMPATT diode (Chapter 8), and detect optical signals, as in an

avalanche photodetector (Chapter 10).

3.6.1 Tunneling Effect

*When a high electric field is applied to a p-n junction in the reverse direction, a

valence electron can make a transition from the valence band to the conduction

band, as shown in Fig. 22a.

This process, in which an electron penetrates through the energy bandgap, is called

tunneling.

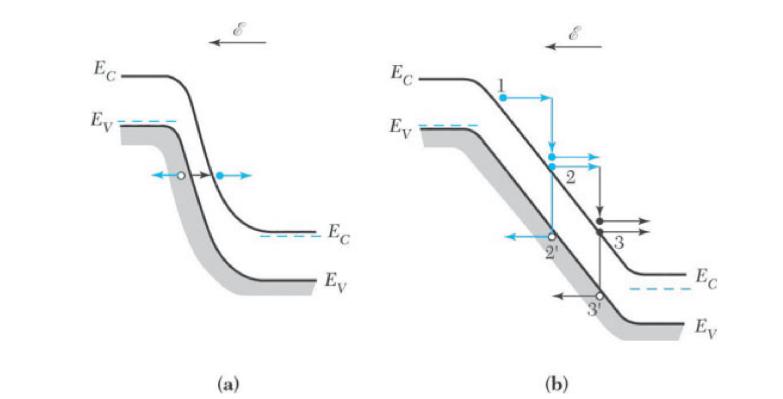


Fig. 22 Energy band diagrams under junction-breakdown conditions. (a) Tunneling effect. (b) Avalanche multiplication.

Tunneling occurs only if the electric field is very high.

*The typical field for silicon and gallium arsenide is about 10⁶ V/cm or higher.

To achieve such a high field, the doping concentrations for both p- and n-regions must be quite high (> 5 × 10¹⁷ cm⁻³).

The breakdown mechanisms for silicon and gallium arsenide junctions with

breakdown voltages of less than about $4E_q/q$, where E_q is the bandgap, are the result

of the tunneling effect.

* For junctions with breakdown voltages in excess of $\frac{\partial E_{\alpha}}{q}$, the breakdown mechanism

is the result of avalanche multiplication.

*At voltages between 4 and $\frac{\partial E_q}{q}$, the breakdown is due to a mixture of both

avalanche multiplication and tunneling.

3.6.2 Avalanche Multiplication

The avalanche multiplication process is illustrated in Fig. 22b.

* The p-n junction, such as a p^+ -n one-sided abrupt junction with a doping

concentration of $N_D \cong 10^{17} \text{ cm}^{-3}$ or less, is under reverse bias.

*A thermally generated electron in the depletion region (designated by 1) gains

kinetic energy from the electric field.

If the field is sufficiently high, the electron can gain enough kinetic energy that on

collision with an atom, it can break the lattice bonds, creating an electron-hole pair

(2 and 2').

The newly created electron and hole both acquire kinetic energy from the field and

create additional electron-hole pairs (e.g., 3 and 3').

These in turn continue the process, creating other electron-hole pairs.

This process is therefore called avalanche multiplication.